## SAN DIEGO AIR POLLUTION CONTROL DISTRICT

| SUPPLEMENTAL APPLICATIO | N |  |  |
|-------------------------|---|--|--|
| INFORMATION             |   |  |  |
| FEE SCHEDULE            |   |  |  |
| 32 A                    |   |  |  |
| FEE SCHEDULE            |   |  |  |

| San Diego APCD Use Only |
|-------------------------|
| Appl. No.:              |
| ID No.:                 |

## **COPPER ETCHING**

| Equ  | upment Adar   | ess:   |  |                |                  |                          |  |
|--|---|--|--|----------------|------------------|--------------------------|--|
| A.   | EQUIPMENT DESCRIPTION List equipment used in the process:               |  |  |                |                  |                          |  |
|  | Equipmen  | t  | <u>Manufacturer</u>                                  | Model          |                  | <u>S/N</u>               |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
| ъ  | <b>PROGE</b> GG   | DECCRIPTION.   |  |                |                  |                          |  |
| В.   | <b>PROCESS</b>  | <b>DESCRIPTION</b>   |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
|  |   |  |  |                |                  |                          |  |
| С.   |   | NG SCHEDULE  |  |                |                  |                          |  |
|  | <u>OPERATIN</u>   |  |  |                | Wks/Yr           |                          |  |
|  | OPERATIN  | NG SCHEDULE  |  |                | Wks/Yr<br>Wks/Yr |                          |  |
|  | OPERATION  Average:  Maximum: _   | NG SCHEDULE  Hrs/Day   | Days/Wk<br>Days/Wk                                   |                |                  |                          |  |
| C. D.  | OPERATION  Average:  Maximum: _  ETCHING                                | NG SCHEDULE  Hrs/Day  Hrs/Day  SOLUTION INF  | Days/Wk<br>Days/Wk                                   |                |                  |                          |  |
| <ul><li>С.</li><li>D.</li><li>Туре</li></ul> | OPERATION Average: Maximum: _ ETCHING e of Etching Sol                  | NG SCHEDULE  Hrs/Day  Hrs/Day  SOLUTION INF  ution:                                | Days/Wk<br>Days/Wk<br><b>ORMATION</b>                |                |                  |                          |  |
| <ul><li>С.</li><li>D.</li><li>Туре</li></ul> | OPERATION Average: Maximum: _ ETCHING the of Etching Solution Temperate | MG SCHEDULE  Hrs/Day  Hrs/Day  SOLUTION INF  ution:  ure of Etching Solut  Product | Days/WkDays/Wk  ORMATION  tion:°F; or  Product       | °C<br>Max. Use | Wks/Yr           |                          |  |
| <ul><li>С.</li><li>D.</li><li>Туре</li></ul> | OPERATION Average: Maximum: _ ETCHING e of Etching Sol                  | NG SCHEDULE Hrs/DayHrs/Day  SOLUTION INF  ution: ure of Etching Solut              | Days/Wk<br>Days/Wk<br><b>ORMATION</b><br>:ion:°F; or | °C<br>Max. Use | Wks/Yr           | Cu <sub>1</sub> /C (g/l) |  |
| <ul><li>С.</li><li>D.</li><li>Туре</li></ul> | OPERATION Average: Maximum: _ ETCHING the of Etching Solution Temperate | MG SCHEDULE  Hrs/Day  Hrs/Day  SOLUTION INF  ution:  ure of Etching Solut  Product | Days/WkDays/Wk  ORMATION  tion:°F; or  Product       | °C<br>Max. Use | Wks/Yr           |                          |  |
| <ul><li>С.</li><li>D.</li><li>Туре</li></ul> | OPERATION Average: Maximum: _ ETCHING the of Etching Solution Temperate | MG SCHEDULE  Hrs/Day  Hrs/Day  SOLUTION INF  ution:  ure of Etching Solut  Product | Days/WkDays/Wk  ORMATION  tion:°F; or  Product       | °C<br>Max. Use | Wks/Yr           |                          |  |
| <ul><li>С.</li><li>D.</li><li>Туре</li></ul> | OPERATION Average: Maximum: _ ETCHING the of Etching Solution Temperate | MG SCHEDULE  Hrs/Day  Hrs/Day  SOLUTION INF  ution:  ure of Etching Solut  Product | Days/WkDays/Wk  ORMATION  tion:°F; or  Product       | °C<br>Max. Use | Wks/Yr           |                          |  |

| 6  | Total Average of Materials used:   | gal/month   |  |  |
|----|--|---|--|--|
| 7  | Additional Anhydrous Ammonia (NH3)/liter o   | f etching solution:   |  |  |
| 8  | lb/day (Max.);   | lb/month (Avg.);  | lb/year (Avg.); <b>or</b>  |  |
| 9  | gal/day (Max.);  | gal/month (Avg.);   | gal/year (Avg.)  |  |
|    | M1: Molarity M2: Molarity Cu1 (gram/liter):  Of NH3 in original etch of NH3 in original etch Copper Concentration in Copper Concentration in | (H3)/liter of etching soluting solution includes freing solution which will in original etching solution remaining etching solution | tion te NH3 and complexed NH3 the recycled on ution which will be recycled |  |
| 20 | pH range for normal operation (if applicable):   |   |  |  |
| 1  | pH range for remaining etching solution which  | ı wıll be:  |  |  |
| 2  | E. <u>EMISSION CONTROL EQUIPMEN</u>  | <u>T</u>  |  |  |
| 3  | Describe how process equipment is vented:  |   |  |  |
| ļ  |  |   |  |  |
|    |  |   |  |  |
|    | Length of Venting Cycle:minutes  |   |  |  |
| ,  | Description of Control Equipment (if applicable  | le):  |  |  |
|    |  |   |  |  |
|    |  |   |  |  |
|    |  |   |  |  |
|    |  |   |  |  |
|    | If control equipment is a water scrubber, is the   | water pH enhanced?  | ☐ Yes ☐ No   |  |
|    | Is the water scrubber equipped with a permane  | ent pH meter?  Yes  | ☐ No Specify pH level:   |  |
|    | Specify type of chemical used to maintain pH l   | -   |  |  |
|    | Control Efficiency for NH3:  | ·   |  |  |
| 5  |  |   |  |  |
| 6  | F. STACK DATA  |   |  |  |
|    |  |   |  |  |

| <u>Parameter</u>               | <u>Stack #1</u> | <u>Stack #2</u> | <u>Stack #3</u> |
|--------------------------------|-----------------|-----------------|-----------------|
| Height above top of bldg. (ft) |                 |                 |                 |
| Height above ground (ft)       |                 |                 |                 |
| Stack Diameter (ft)            |                 |                 |                 |
| Exhaust gas temp. (°F)         |                 |                 |                 |
| Exhaust gas flow (scfm)        |                 |                 |                 |
| Building dimensions            | Lx              | Wx              | H ft            |

| 37 <b>G.</b> | FACILITY DATA |
|--------------|---------------|
|              |               |

Please attach a site sketch or drawing and provide the following information:

- Distance from emission point(s) to the nearest property line.
- Distance from emission point(s) to the nearest residence.
- Distance from emission point(s) to the nearest significant terrain feature.
- Distance from emission point(s) to other large buildings in the vicinity.
  - Attach a copy of Thomas Bros. map page and identify your source location.
  - Attach a sketch of the process equipment configuration and associated ventilation equipment including duct sizes and fans.

| 42 | Name of Preparer: | Title: |  |
|----|-------------------|--------|--|
|    |                   |        |  |
|    |                   |        |  |
| 43 | Phone No.: (      | Date:  |  |

## NOTE TO APPLICANT:

Before acting on an application for Authority to Construct or Permit to Operate, the District may require further information, plans, or specifications. Forms with insufficient information may be returned to the applicant for completion, which will cause a delay in application processing and may increase processing fees. The applicant should correspond with equipment and material manufacturers to obtain the information requested on this supplemental form.